

# UNISONIC TECHNOLOGIES CO., LTD

UTT12NN10 Power MOSFET

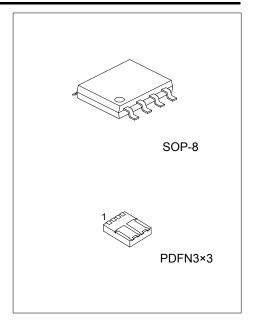
# 2.5A, 100V DUAL N-CHANNEL ENHANCEMENT MODE POWER MOSFET

#### **■** DESCRIPTION

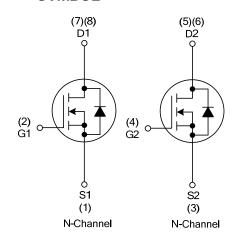
The UTC **UTT12NN10** is a N-channel Power MOSFET, it uses UTC's advanced technology to provide the customers with low Rdson characteristic by high cell density trench technology.

#### **■** FEATURES

- \*  $R_{DS(ON)} \le 0.28 \Omega @ V_{GS} = 10V, I_D = 2.0A$
- \* Fast Switching Speed
- \* Simple Drive Requirement



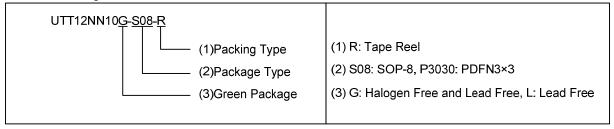
#### ■ SYMBOL



#### **■ ORDERING INFORMATION**

Ordering Number		Dealtes	Pin Assignment							Daaldaa		
Lead Free	Halogen Free	Package	Package 1 2		3	4	5	6	7	8	Packing	
UTT12NN10L-S08-R	UTT12NN10G-S08-R	SOP-8	S1	G1	S2	G2	D2	D2	D1	D1	Tape Reel	
UTT12NN10L-P3030-R	UTT12NN10G-P3030-R	PDFN3×3	S1	G1	S2	G2	D2	D2	D1	D1	Tape Reel	

Note: Pin Assignment: G: Gate D: Drain S: Source



www.unisonic.com.tw 1 of 6

# **■** MARKING

SOP-8	PDFN3×3					
8 7 6 5  UTC	UTT 12NN10  • □□□□  Date Code					

# ■ **ABSOLUTE MAXIMUM RATINGS** (T<sub>A</sub>=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		$V_{DSS}$	100	V
Gate-Source Voltage		$V_{GSS}$	±20	V
Drain Current	Continuous	I <sub>D</sub>	2.5	Α
	Pulsed (Note 2)	I <sub>DM</sub>	10	Α
Peak Diode Recovery dv/dt (Note 3)		dv/dt	2.3	V/nS
Power Dissipation	SOP-8		1.6	W
	PDFN3×3	P <sub>D</sub>	2.0	W
Junction Temperature		TJ	+150	°C
Storage Temperature		T <sub>STG</sub>	-55 ~ <b>+</b> 150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3.  $I_{SD} \le 2.0 \text{A}$ , di/dt  $\le 200 \text{A}/\mu \text{s}$ ,  $V_{DD} \le V_{(BR)DSS}$ ,  $T_J = 25 ^{\circ} \text{C}$ .

#### **■ THERMAL DATA**

PARAMETER		SYMBOL	RATINGS	UNIT		
Junction to Ambient	SOP-8	0	78	°C/W		
	PDFN3×3	$\Theta_{JA}$	62.5	°C/W		

Note: Device mounted on FR-4 substrate P<sub>C</sub> board, 2oz copper, with 1inch square copper plate.

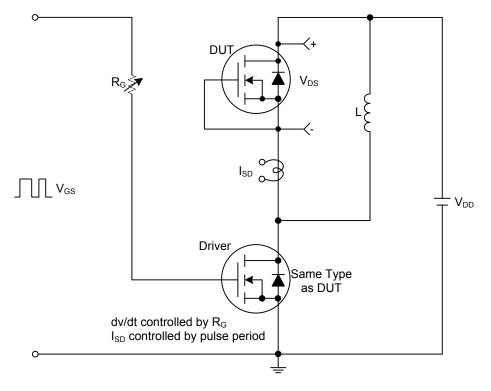
## ■ ELECTRICAL CHARACTERISTICS (T<sub>J</sub>=25°C, unless otherwise specified)

PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage		$BV_{DSS}$	$V_{GS}$ =0V, $I_D$ =250 $\mu$ A	100			V	
Drain-Source Leakage Current		$I_{DSS}$	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V			1	μΑ	
Gate-Source Leakage Current	Forward	I <sub>GSS</sub>	V <sub>DS</sub> =0V ,V <sub>GS</sub> =20V			100	nA	
	Reverse		$V_{DS}$ =0V , $V_{GS}$ =-20V			-100	nA	
ON CHARACTERISTICS								
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$ , $I_D=250\mu A$	1.0		3.0	V	
Drain-Source On-State Resistance		R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =2.0A			0.28	Ω	
DYNAMIC PARAMETERS								
Input Capacitance		C <sub>ISS</sub>			400		pF	
Output Capacitance		Coss	$V_{GS}$ =0V, $V_{DS}$ =25V, f=1.0MHz		33		pF	
Reverse Transfer Capacitance		C <sub>RSS</sub>			26		pF	
SWITCHING PARAMETERS								
Total Gate Charge (Note 1)		$Q_{G}$	$V_{DS}$ =50V, $V_{GS}$ =10V, $I_{D}$ =1.3A,		40		nC	
Gate-Source Charge		$Q_GS$	I <sub>D</sub> =100μA		2.0		nC	
Gate-Drain Charge		$Q_GD$	(Note 1, 2)		3.0		nC	
Turn-ON Delay Time (Note 1)		$t_{D(ON)}$			29		ns	
Turn-ON Rise Time		t <sub>R</sub>	$V_{DS}$ =30V, $V_{GS}$ =10V, $I_{D}$ =0.5A,		26		ns	
Turn-OFF Delay Time		t <sub>D(OFF)</sub>	R <sub>G</sub> =25Ω (Note 1, 2)		165		ns	
Turn-OFF Fall Time		$t_{F}$			37		ns	
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS								
Maximum Body-Diode Continuous Current		I <sub>S</sub>				2.5	Α	
Maximum Body-Diode Pulsed Current		I <sub>SM</sub>				10	Α	
Drain-Source Diode Forward Voltage (Note 1)		$V_{SD}$	I <sub>S</sub> =1.5A, V <sub>GS</sub> =0V			1.3	V	
Body Diode Reverse Recovery Time (Note 1)		t <sub>rr</sub>	I <sub>S</sub> =2.0A, V <sub>GS</sub> =0V,		210		ns	
Body Diode Reverse Recovery Charge		$Q_{rr}$	dI <sub>F</sub> /dt=50A/µs		170		nC	

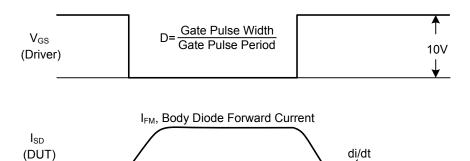
Notes: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle ≤ 2%.

2. Essentially independent of operating temperature.

# **■ TEST CIRCUITS AND WAVEFORMS**

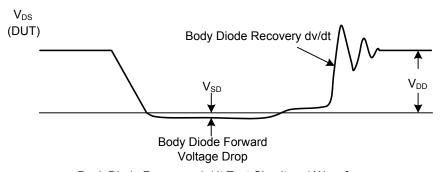


## Peak Diode Recovery dv/dt Test Circuit



Body Diode Reverse Current

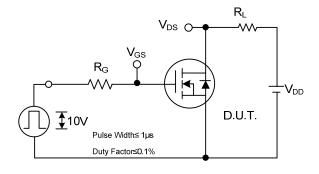
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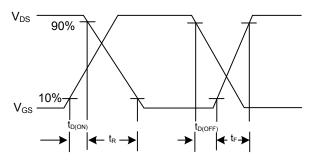


Peak Diode Recovery dv/dt Test Circuit and Waveforms

Peak Diode Recovery dv/dt Waveforms

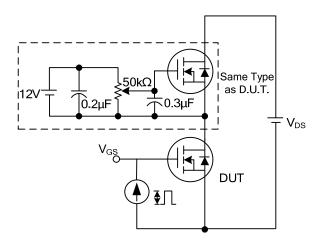
## **■ TEST CIRCUITS AND WAVEFORMS**

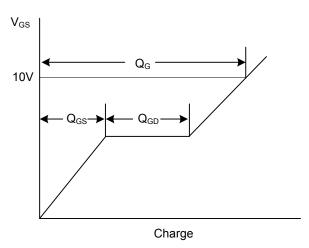




**Switching Test Circuit** 

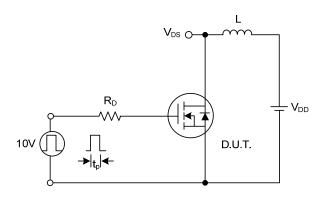
**Switching Waveforms** 

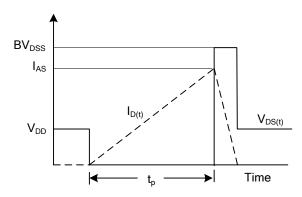




**Gate Charge Test Circuit** 

**Gate Charge Waveform** 





**Unclamped Inductive Switching Test Circuit** 

**Unclamped Inductive Switching Waveforms** 

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